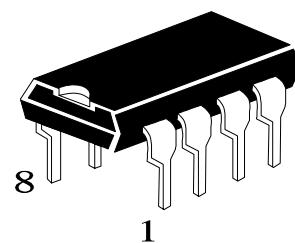


**2048 x 8 -Bit CMOS EEPROM with I<sup>2</sup>C-bus interface**

The INF85116N is an 16-Kbits (2048 x 8-bit) floating gate Electrically Erasable Programmable Read Only Memory (EEPROM). Power consumption is low due to the full CMOS technology used. The programming voltage is generated on-chip, using a voltage multiplier. As data bytes are received and transmitted via the serial I<sup>2</sup>C-bus, a package using eight pins is sufficient. Only one INF85116N device is required to support all eight blocks of 256 x 8-bit each.

**FEATURES**

- Low power CMOS
  - maximum active current 1.0 mA
  - maximum standby current 10 µA (at 5.5 V), typical 4 µA
- Non-volatile storage of 16-Kbits organized as eight blocks of 256x8-bits during 20 years (at 55°C)
- Single supply (Ucc=2,7 ÷ 5,5 V);
- Automatically increased word's address
- On-chip voltage multiplier
- Serial input/output I<sup>2</sup>C-bus
  - 1000000 ERASE/WRITE cycles per byte
  - Internal timer for writing (no external components)
  - Write operations: multi byte write mode to 32 bytes
  - Write - protection input
  - Power-on-reset

Temperature range: -40°C ÷ +85°C

**PIN DESCRIPTION**

<b>Symbol</b>	<b>Pin</b>	<b>Description</b>
n. c.	1	not connected
n. c.	2	not connected
n. c.	3	not connected
Uss	4	negative supply voltage
SDA	5	serial data input/output (I <sup>2</sup> C-bus)
SCL	6	serial clock input (I <sup>2</sup> C-bus)
WP	7	write - protection input
Ucc	8	positive supply voltage

**PIN CONFIGURATION**

n. c.	1	8	Ucc
n. c.	2	7	WP
n. c.	3	6	SCL
Uss	4	5	SDA

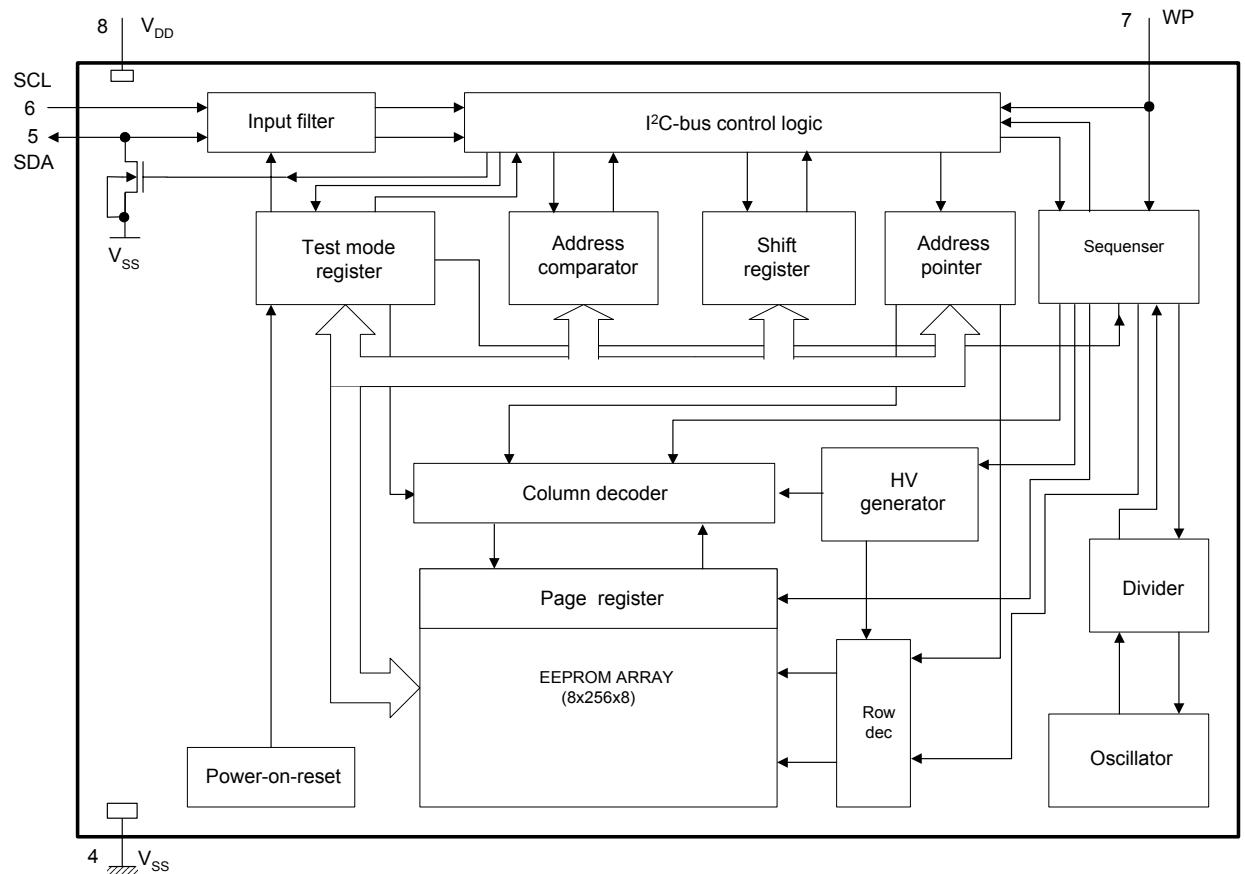
**INF85116N**

**Table 1. Quick reference data**

<b>Symbol</b>	<b>Parameter</b>	<b>min</b>	<b>max</b>	<b>Unit</b>

$U_{DD}$	Supply voltage	2.7	5.5	V
$I_{OL}$	LOW level output current	-	6	mA
$T_{amb}$	Operating ambient temperature	-40	+85	°C

## BLOCK DIAGRAM



**Table 2. Limiting values**

Symbol	Parameter	min	max	Unit
$U_{DD}$	Supply voltage	-0.3	6.5	V
$U_i$	Input voltage on any pin $/Z_i/ > 500 \Omega$	-0.8	6.5	V
$I_i$	Input current on any pin	-	1	mA
$I_o$	Output current	-	10	mA
$T_{stg}$	Storage temperature	-65	+150	°C

**Table 3. Characteristics**

Symbol	Parameter	Conditions	min	max	Unit
$I_{DD(st)}$	Standby supply current	$U_{DD} = 2.7V$ $U_{DD} = 5.5V$	-	6 10	$\mu A$ $\mu A$
$I_{CCR}$	Supply current READ	$f_{SCL}=400\text{kHz}$ , $U_{DD} = 5.5V$	-	1	mA
$I_{CCW}$	Supply current E / W	$f_{SCL}=400\text{kHz}$ , $U_{DD} = 5.5V$	-	1	mA
<b>WP input (pin 7)</b>					
$U_{IL}$	LOW level input voltage		-0.8	$+0.1U_{DD}$	V
$U_{IH}$	HIGH level input voltage		$0.9U_{DD}$	$U_{DD}+0.8$	V
<b>SCL input (pin 6)</b>					
$U_{IL}$	LOW level input voltage		-0.8	$+0.3U_{DD}$	V
$U_{IH}$	HIGH level input voltage		$0.7U_{DD}$	6.5	V
$I_{LI}$	Input leakage current	$U_I=U_{DD}$ or $U_{SS}$	-	$\pm 1$	$\mu A$
$f_{SCL}$	Clock input frequency		0	400	kHz
$t_{sp}$	Pulse width of spikes suppressed by filter		0	100	ns
$C_I$	Input capacitance	$U_I= U_{SS}$	-	7	pF
<b>SDA input/output (pin 5)</b>					
$U_{IL}$	LOW level input voltage		-0.8	$0.3U_{DD}$	V
$U_{IH}$	HIGH level input voltage		$0.7U_{DD}$	6.5	V
$U_{OL1}$ $U_{OL2}$	LOW level output voltage	$I_{OL}=3mA$ , $U_{DD} = U_{DD} (\text{min})$ $I_{OL}=6mA$ , $U_{DD} = U_{DD} (\text{min})$	-	0.4 0.6	V
$I_{LO}$	Output leakage current	$U_{OH}=U_{DD}$	-	1	$\mu A$
$t_{O(F)}$	Output fall time from $U_{IH\text{min}}$ to $U_{IL\text{max}}$	with up to 3mA sink current at $U_{OL1}$ with up to 6mA sink current at $U_{OL2}$	$20+0.1 C_B^*$ $20+0.1 C_B$	250 250	ns ns
$t_{SP}$	Pulse width of spikes suppressed by filter		0	100	ns
$C_I$	Input capacitance	$U_I=0V$	-	10	pF
$t_{E/W}$	E/W cycle time		-	10	ms
$N_{E/W}$	E/W cycle per byte	$T_{amb}=(-40-+85)^\circ\text{C}$ , $T_{amb}=22^\circ\text{C}$	100000 1000000	-	
$t_S$	Data retention time	$T_{amb} = 55^\circ\text{C}$	20	-	years

\* - The bus capacitance ranges from 10 to 400pF (  $C_B$  = total capacitance of one bus line in pF)

**Table 4. I<sup>2</sup>C-bus characteristics**

Symbol	Parameter	Condi-tions	Standard mode		Fast mode		Unit
			min	max	min	max	
f <sub>SCL</sub>	Clock frequency		0	100	0	400	kHz
t <sub>BUF</sub>	Time the bus must be free before	-	4.7	-	1.3	-	μs
t <sub>HD, STA</sub>	START condition hold time after which first clock pulse is generated	-	4.0	-	0.6	-	μs
t <sub>LOW</sub>	LOW level clock period	-	4.7	-	1.3	-	μs
t <sub>HIGH</sub>	HIGH level clock period	-	4.0	-	0.6	-	μs
t <sub>SU, STA</sub>	Set-up time for START condition	repeated start	4.7	-	0.6	-	μs
t <sub>HD, DAT</sub>	Data hold time for CBUS compatible masters	-	5	-	-	-	μs
t <sub>HD, DAT</sub>	Data hold time for I <sup>2</sup> C - bus devices	note 1	0	-	0	-	ns
t <sub>SU, DAT</sub>	Data set-up time	-	250	-	100	-	ns
t <sub>R</sub>	SDA and SCL rise time	-	-	1000	20+0. 1 C <sub>b</sub> <sup>(2)</sup>	300	ns
t <sub>F</sub>	SDA and SCL fall time	-	-	300	20+0. 1 C <sub>b</sub> <sup>(2)</sup>	300	ns
t <sub>SU, STO</sub>	Set-up time for STOP condition	-	4.0	-	0.6	-	μs

Notes:

1. The hold time required (not greater than 300 ns) to bridge the undefined region of the falling edge of SCL must be internally provided by a transmitter.
2. C<sub>b</sub> = total capacitance of one bus line in pF.